





Data Sheet Dexnyl<sup>©</sup> 240 TPI-Powders Nat.

## **Product Description**

Thermoplastic Polyimide (TPI), natural granule suitable for molding and compounding

## **Applications**

- Suitable for ultra-high temperature, high pressure, compartment temperatures, insulation, and high friction applications
- To produce self-lubricant and wear resistance parts for high temperatures
- High temperature bearing cages, seal rings, gaskets, compressor parts, etc.
- To produce non-toxic fire retardant products

Properties	Units	Dexnyl© 240 TPI
Density	g/cm <sup>3</sup>	1.33
Melting point	°C	385
Glass Transistion Temperature	°C	240
Thermal Expansion Coefficient	10 <sup>-5</sup> /°C	6.0
Tensile Strength ≥	MPa	100.0
Tensile Strain at Break	%	24
Flexural Strength≥	MPa	140.0
Flexural Modulus≥	GPa	2.8
Charpy Impact Strength (Unnotched) ≥	KJ/m <sup>2</sup>	110.0
Friction Coefficient	-	0.20-0.25
Volume Resistivity	Ω.m	1.0×10 <sup>15</sup>
Shore D Hardness≥	HD	85.0
Water absorption <	%	0.3

Distributed by

## **BIEGLO GmbH**

Bahrenfelder Straße 242 22765 Hamburg +49 40 4011 30000 info@bieglo.com www.bieglo.com www.polyimide-shop.de The specified values are established from average values of several tests and they correspond to our today's knowledge. They are only to be used as information about our products and as help for the material selection. With these values, we do not ensure specific properties, or the suitability for certain application. No warranty, representation, guarantee or legally binding product description is provided by publishing this informational data.

For information about divergent properties do not hesitate to contact us. On request we advise you regarding the most appropriate component design and the definition of material specifications more suitable to your application data. Notwithstanding, the customer bears all the responsibility for the thorough examination of suitability, efficiency, efficacy and safety of the chosen products in pharmaceutical applications, medical devices or other end uses. Status: June 2019